



Power MOSFETS

DATASHEET

LM20A51PLI3A

P-Channel
Enhancement Mode MOSFET

 Leadpower-semiconductor Corp., Ltd

 sales@leadpower-semi.com

 (03) 6577339 FAX : (03) 6577229

 www.leadpower-semi.com



Quality Management Systems

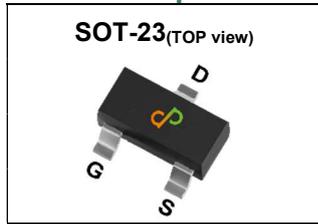
ISO 9001:2015 Certificate

LM20A51PLI3A

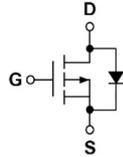


P-Channel Enhancement Mode MOSFET

Pin Description



Symbol



Product Summary

Symbol	P-Channel	Unit
V_{DSS}	-20	V
$R_{DS(ON)-Max}$	168	mΩ
I_D	-1.9	A

Feature

- Low Q_g and Q_{gd}
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered systems.

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM20A51PLI3A	SOT-23	Tape & Reel	3000 / Tape & Reel	10□□□

Note : □□□ = Lot Code

Absolute Maximum Ratings (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	P-Channel	Unit	
V_{DSS}	Drain-Source Voltage	-20	V	
V_{GSS}	Gate-Source Voltage	±8		
T_J	Maximum Junction Temperature	150	°C	
T_{STG}	Storage Temperature Range	-55 to 150	°C	
I_S	Diode Continuous Forward Current	$T_A=25^\circ C$	-1.7	A
$I_{DM}^{\textcircled{1}}$	Pulse Drain Current Tested	$T_A=25^\circ C$	-4.8	A
I_D	Continuous Drain Current	$T_A=25^\circ C$	-1.9	A
		$T_A=70^\circ C$	-1.2	
P_D	Maximum Power Dissipation	$T_A=25^\circ C$	0.9	W
		$T_A=70^\circ C$	0.35	

Thermal Characteristics

Symbol	Parameter	Rating	Unit	
$R_{\theta JA}^{\textcircled{2}}$	Thermal Resistance-Junction to Ambient	Steady State	140	°C/W

Note ① : Max. current is limited by junction temperature

Note ② : Surface Mounted on 1in² FR-4 board with 1oz

P-Channel Electrical Characteristics (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250uA	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-16V, V _{GS} =0V	-	-	-1	uA
V_{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250uA	-0.5	-0.75	-1	V
I_{GSS}	Gate Leakage Current	V _{GS} =±8V, V _{DS} =0V	-	-	±100	nA
R_{DS(ON)} ^③	Drain-Source On-state Resistance	V _{GS} =-4.5V, I _{DS} =-1.5A	-	140	168	mΩ
		V _{GS} =-2.5V, I _{DS} =-1.5A	-	184	239	
		V _{GS} =-1.8V, I _{DS} =-1A	-	250	377	
gfs	Forward Transconductance	V _{DS} =-5V, I _{DS} =-1.5A	-	4.5	-	S
Dynamic Characteristics ^④						
R_G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Freq.=1MHz	-	19	-	Ω
C_{ISS}	Input Capacitance	V _{GS} =0V, V _{DS} =-10V, Freq.=1MHz	-	259	-	pF
C_{OSS}	Output Capacitance		-	24	-	
C_{RSS}	Reverse Transfer Capacitance		-	20	-	
td(ON)	Turn-on Delay Time	V _{GS} =-4.5V, V _{DS} =-10V, I _D =-1A, R _{GEN} =6.8Ω	-	4	-	nS
t_r	Turn-on Rise Time		-	2.4	-	
t_{d(OFF)}	Turn-off Delay Time		-	31	-	
t_f	Turn-off Fall Time		-	10	-	
Q_g	Total Gate Charge	V _{GS} =-2.5V, V _{DS} =-10V I _D =-1.5A	-	2	-	nC
Q_g	Total Gate Charge	V _{GS} =-4.5V, V _{DS} =-10V, I _D =-1.5A	-	3.5	-	
Q_{gs}	Gate-Source Charge		-	0.8	-	
Q_{gd}	Gate-Drain Charge		-	0.7	-	
Source-Drain Characteristics						
V_{SD} ^③	Diode Forward Voltage	I _{SD} =-2A, V _{GS} =0V	-	0.9	1.1	V
t_{rr}	Reverse Recovery Time	I _F =-1A, V _R =0V	-	6.5	-	nS
Q_{rr}	Reverse Recovery Charge	di _F /dt=100A/μs	-	2	-	nC

Note ③ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ④ : Guaranteed by design, not subject to production testing.

P-Channel Typical Characteristics

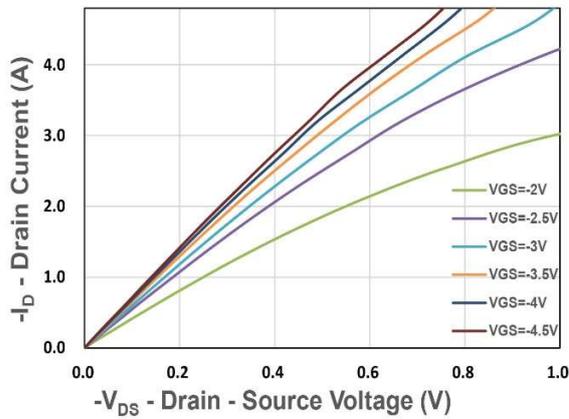


Figure 1. Output Characteristics

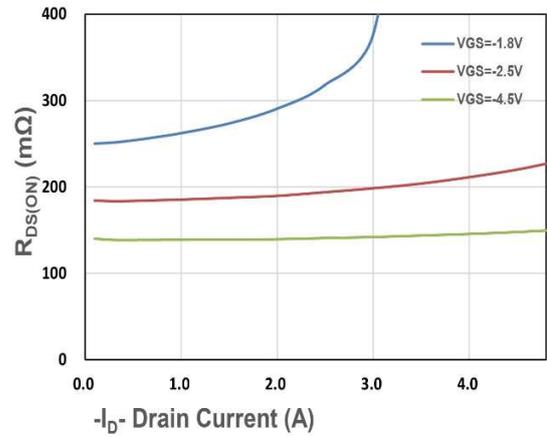


Figure 2. On-Resistance vs. ID

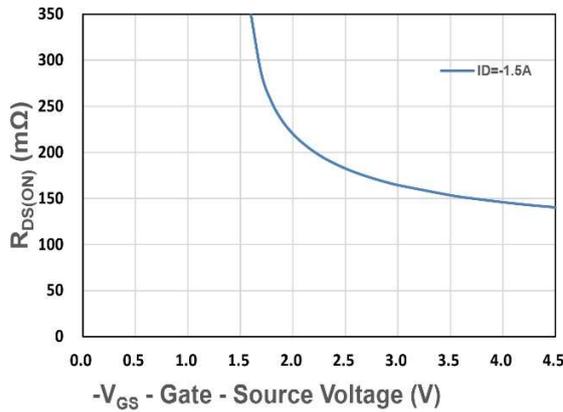


Figure 3. On-Resistance vs. VGS

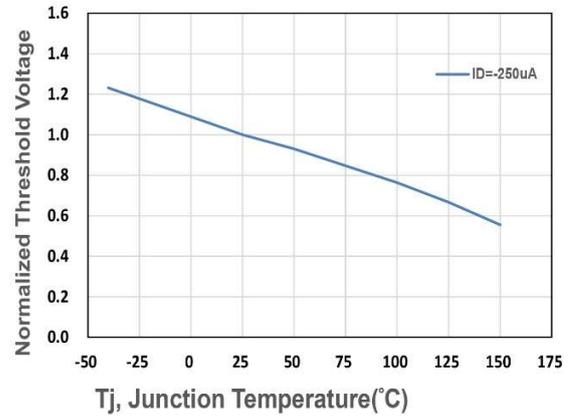


Figure 4. Gate Threshold Voltage

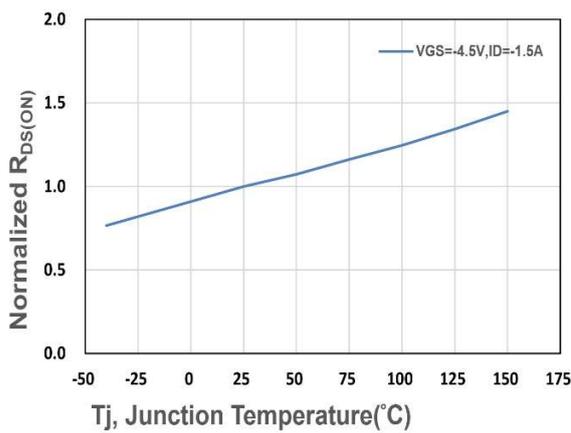


Figure 5. Drain-Source On Resistance

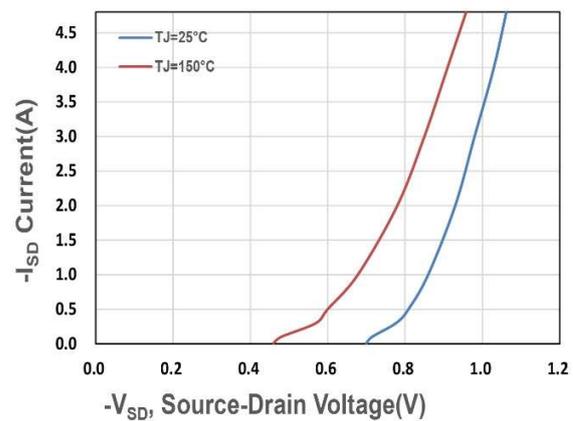


Figure 6. Source-Drain Diode Forward

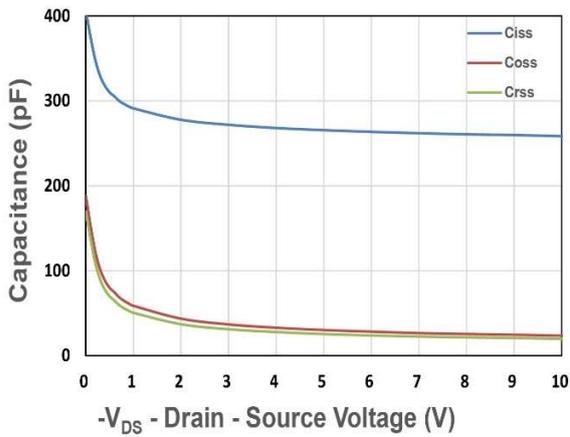


Figure 7. Capacitance

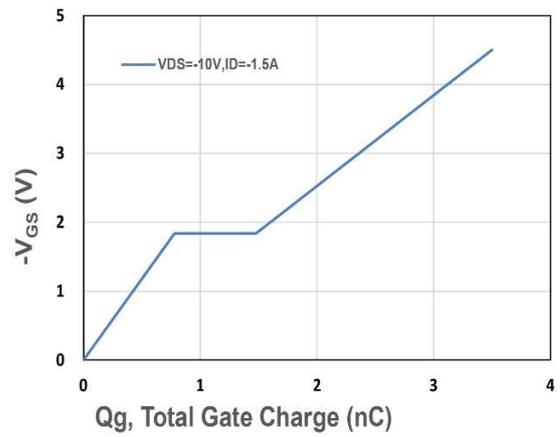


Figure 8. Gate Charge Characteristics

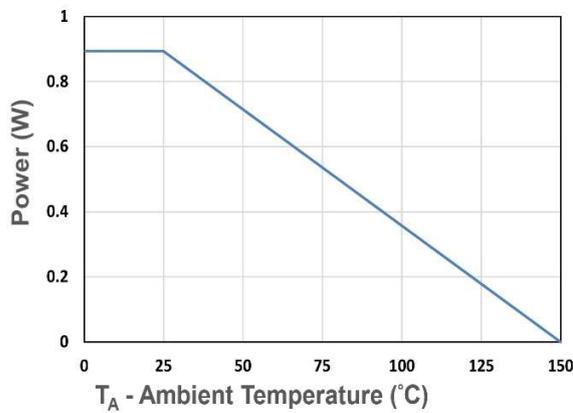


Figure 9. Power Dissipation

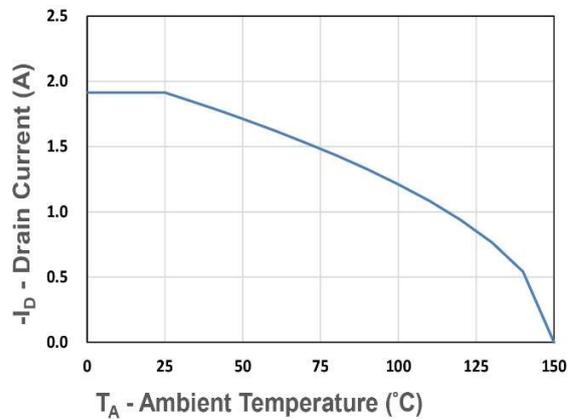


Figure 10. Drain Current

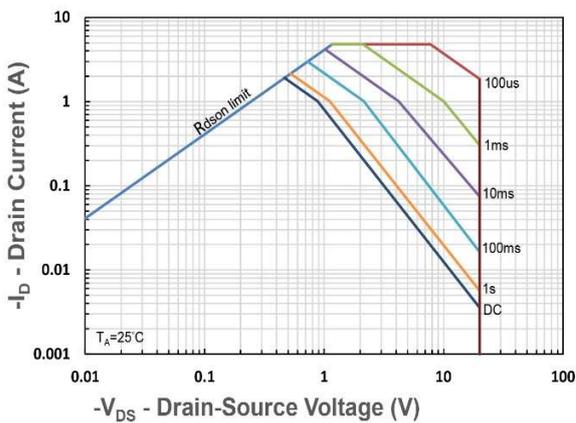


Figure 11. Safe Operating Area

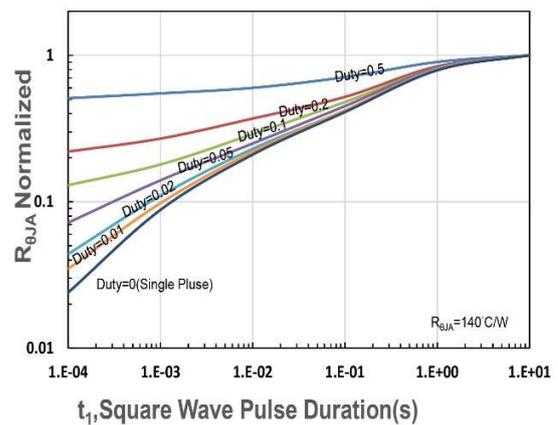


Figure 12. $R_{\theta JA}$ Transient Thermal Impedance